

MJ P-Channel Enhancement Mode Power MOSFET

Description

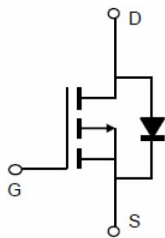
The MJ30P20Q uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. This device is suitable for use as a load switch or in PWM applications.

General Features

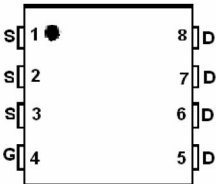
- ◆ $V_{DS}=-30V, I_D=-20A$
 $R_{DS(ON)}<25m\Omega$ @ $V_{GS}=-4.5V$
 $R_{DS(ON)}<15m\Omega$ @ $V_{GS}=-10V$
- ◆ High Power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

Application

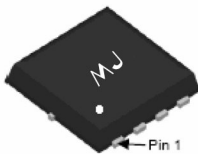
- ◆ PWM applications
- ◆ Load switch
- ◆ Power management



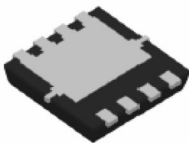
Schematic diagram



pin assignment



Top View



Bottom View

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ30P20Q	MJ30P20Q	DFN3.3X3.3-8L	Ø330mm	12mm	5000 units

Absolute Maximum Ratings (Tc =25 °Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	-20	A
Drain Current-Continuous(Tc =100°C)	$I_{D(100^{\circ}C)}$	-14.1	A
Drain Current-Pulsed ^(Note 1)	I_{DM}	-80	A
Maximum Power Dissipation	P_D	35	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{\theta JA}$	3.57	°C/W
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Electrical Characteristics (T_A =25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =±20V,V _{GS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-1	-1.5	-1.9	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-15A	-	11.5	15	mΩ
		V _{GS} =-4.5V, I _D =-15A	-	18	25	mΩ
Gate resistance	R _G		-	5.2	-	Ω
Forward Transconductance	g _{FS}	V _{DS} =-5V,I _D =-15A	15	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C _{iss}	V _{DS} =-25V,V _{GS} =0V, F=1.0MHz	-	2130	-	PF
Output Capacitance	C _{OSS}		-	302	-	PF
Reverse Transfer Capacitance	C _{rss}		-	227	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-15V, I _D =-15A, V _{GS} =-10V,R _{GEN} =1Ω	-	12	-	nS
Turn-on Rise Time	t _r		-	10	-	nS
Turn-Off Delay Time	t _{d(off)}		-	25	-	nS
Turn-Off Fall Time	t _f		-	13	-	nS
Total Gate Charge	Q _g	V _{DS} =-15V,I _D =-20A, V _{GS} =-10V	-	45.6	-	nC
Gate-Source Charge	Q _{gs}		-	4.6	-	nC
Gate-Drain Charge	Q _{gd}		-	11.1	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V,I _S =-20A	-		-1.2	V

Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

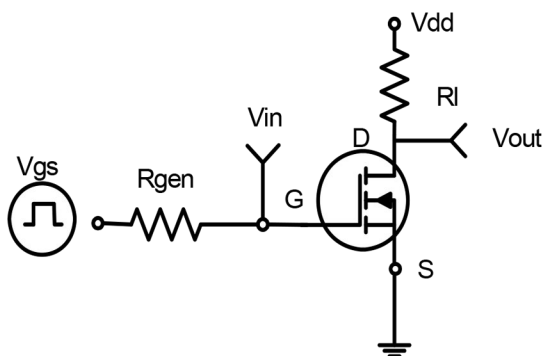


Figure 1 Switching Test Circuit

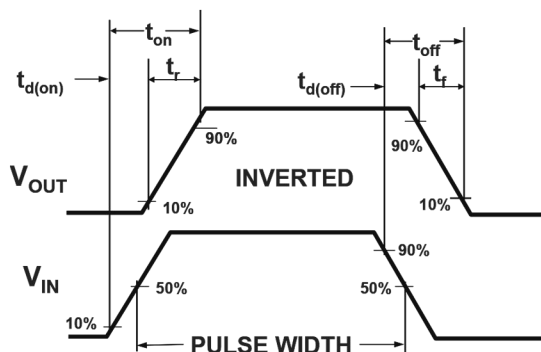
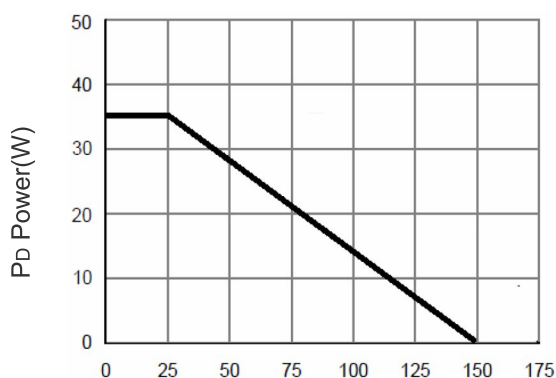
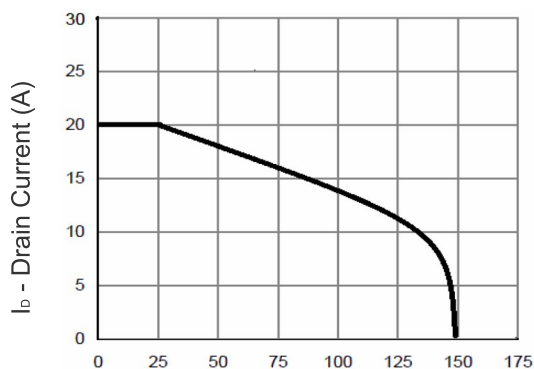


Figure 2 Switching Waveforms



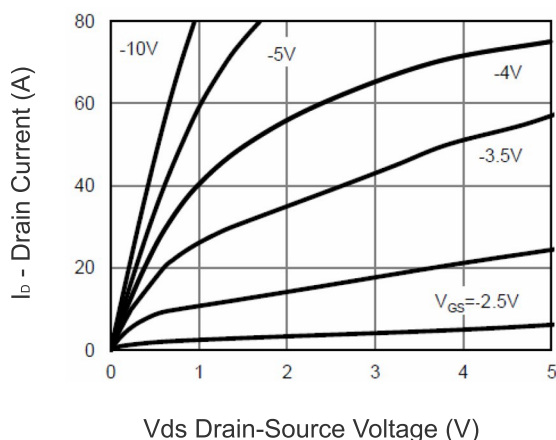
T_J -Junction Temperature(°C)

Figure 3 Power Dissipation



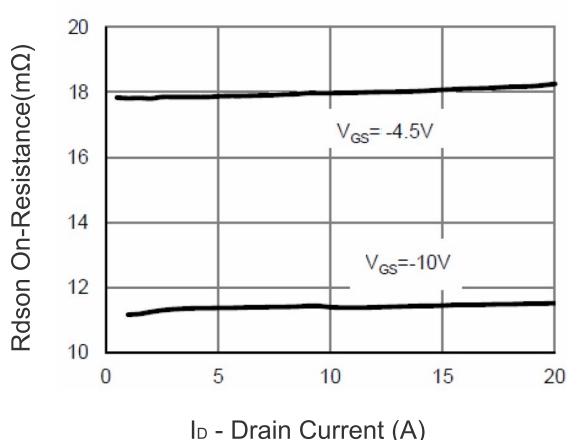
T_J -Junction Temperature(°C)

Figure 4 Drain Current



V_{ds} Drain-Source Voltage (V)

Figure 5 Output Characteristics



I_D - Drain Current (A)

Figure 6 Drain-Source On-Resistance

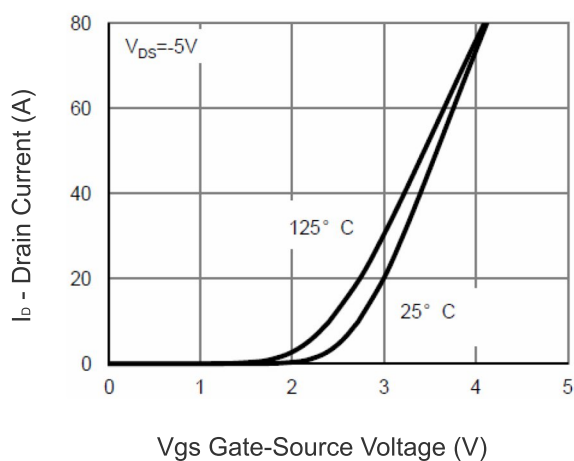


Figure 7 Transfer Characteristics

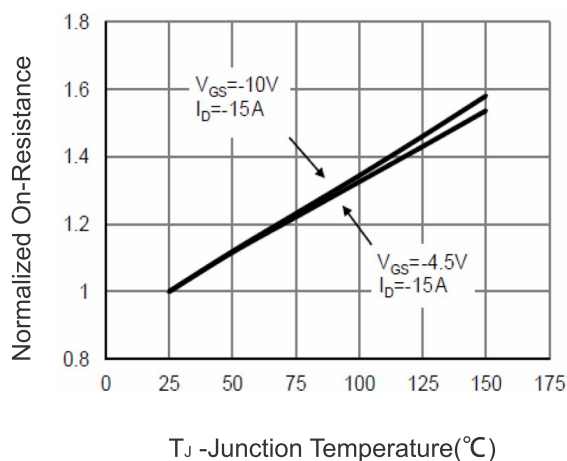


Figure 8 Drain-Source On-Resistance

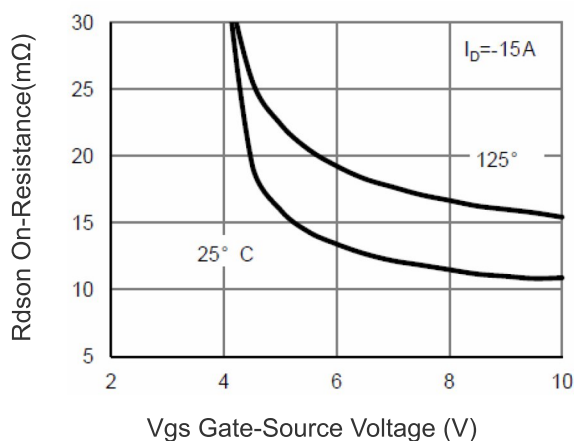


Figure 9 Rdson vs Vgs

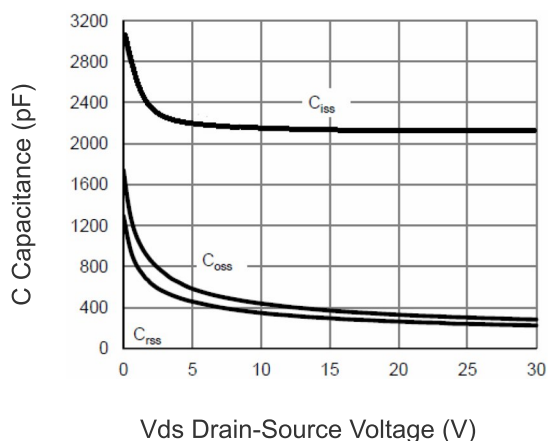


Figure 10 Capacitance vs Vds

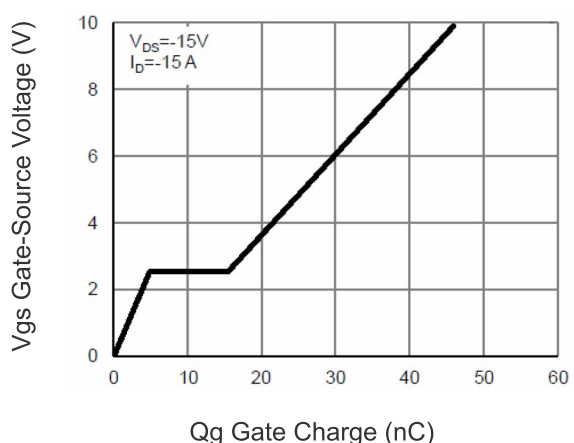


Figure 11 Gate Charge

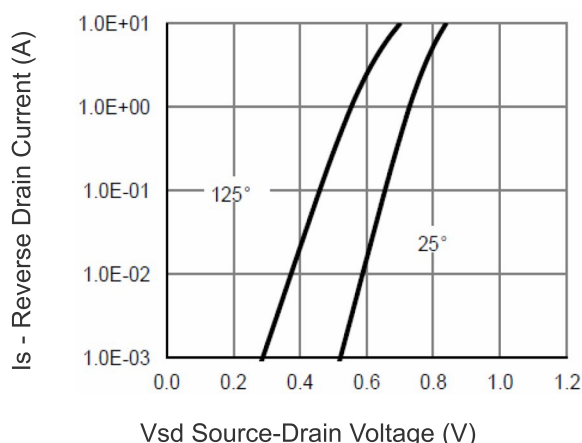


Figure 12 Source- Drain Diode Forward

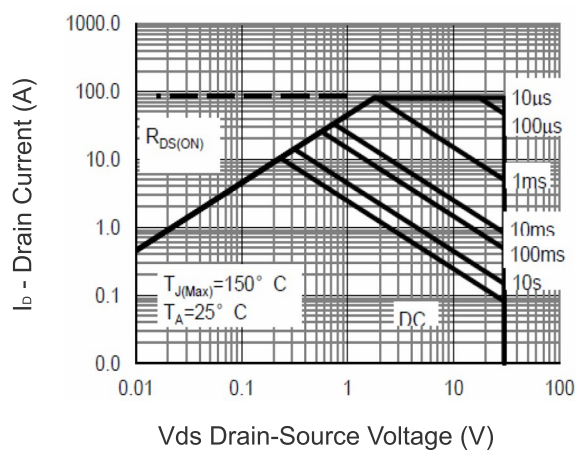


Figure 13 Safe Operation Area

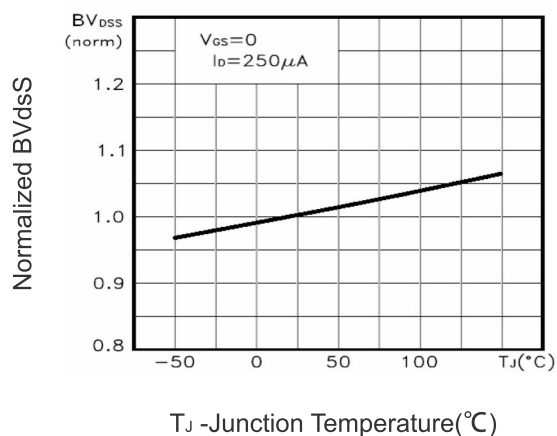
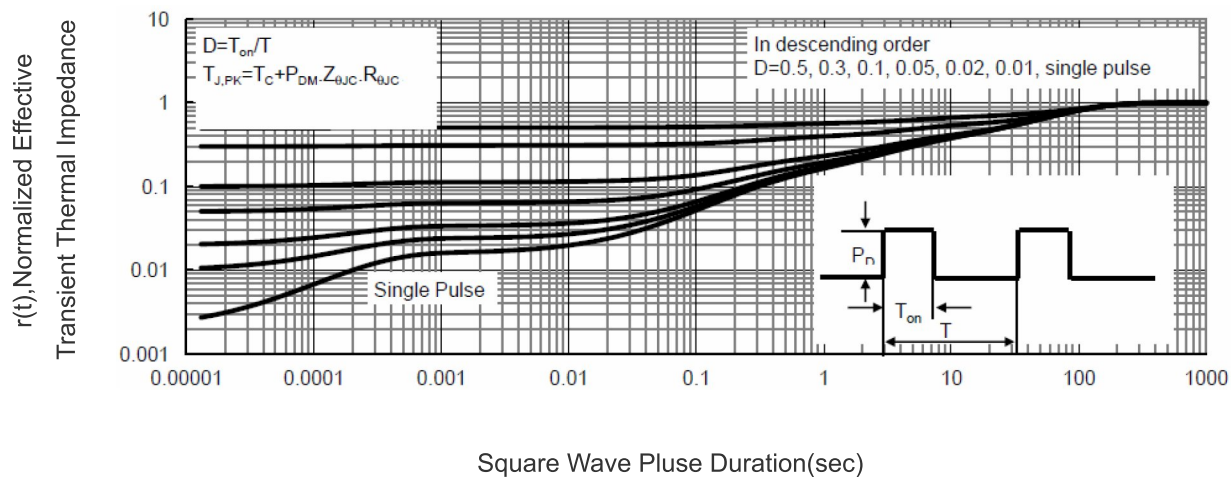
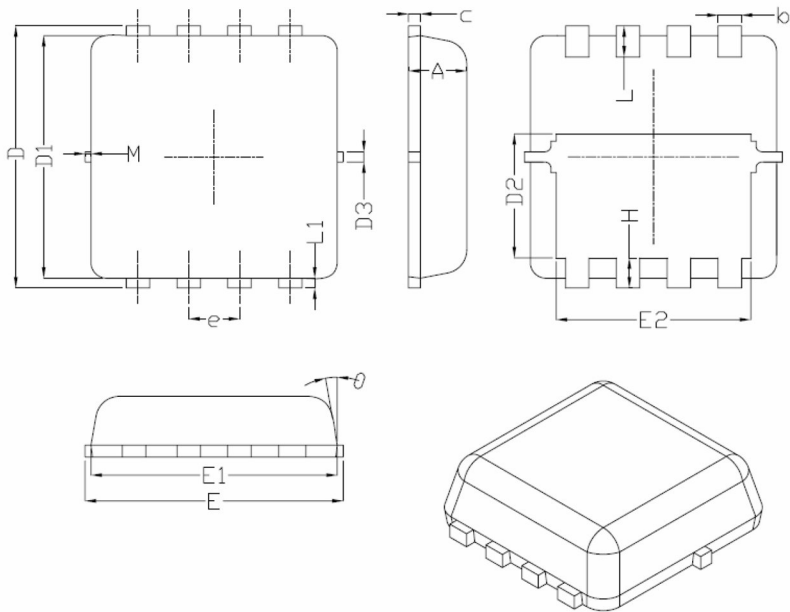

Figure 14 BV_{DS} vs Junction Temperature


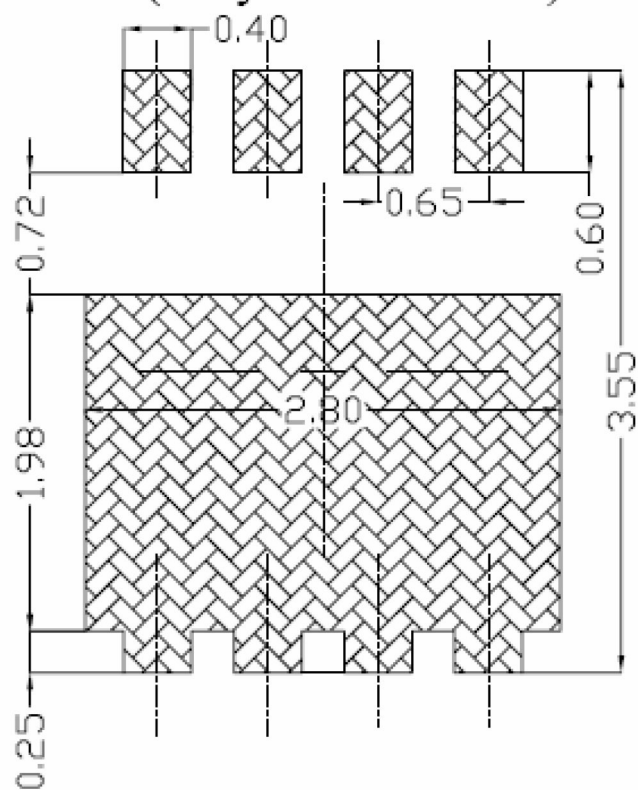
Figure 15 Normalized Maximum Transient Thermal Impedance

DFN3.3X3.3-8L Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°

Land Pattern
(Only for Reference)



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